



# SOT883C

Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.34 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	DFN1006C-3
<b>Package type industry code</b>	DFN1006C-3
<b>Package style descriptive code</b>	SOT (small outline transistor)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-252
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	9-4-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.55	-	0.6	0.65	mm
E	package width	0.95	-	1	1.05	mm
A	seated height	0.32	-	0.34	0.35	mm
A <sub>2</sub>	package height	0.31	-	0.32	0.33	mm
e	nominal pitch	-	-	0.35	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	3	-	



## 2. Package outline

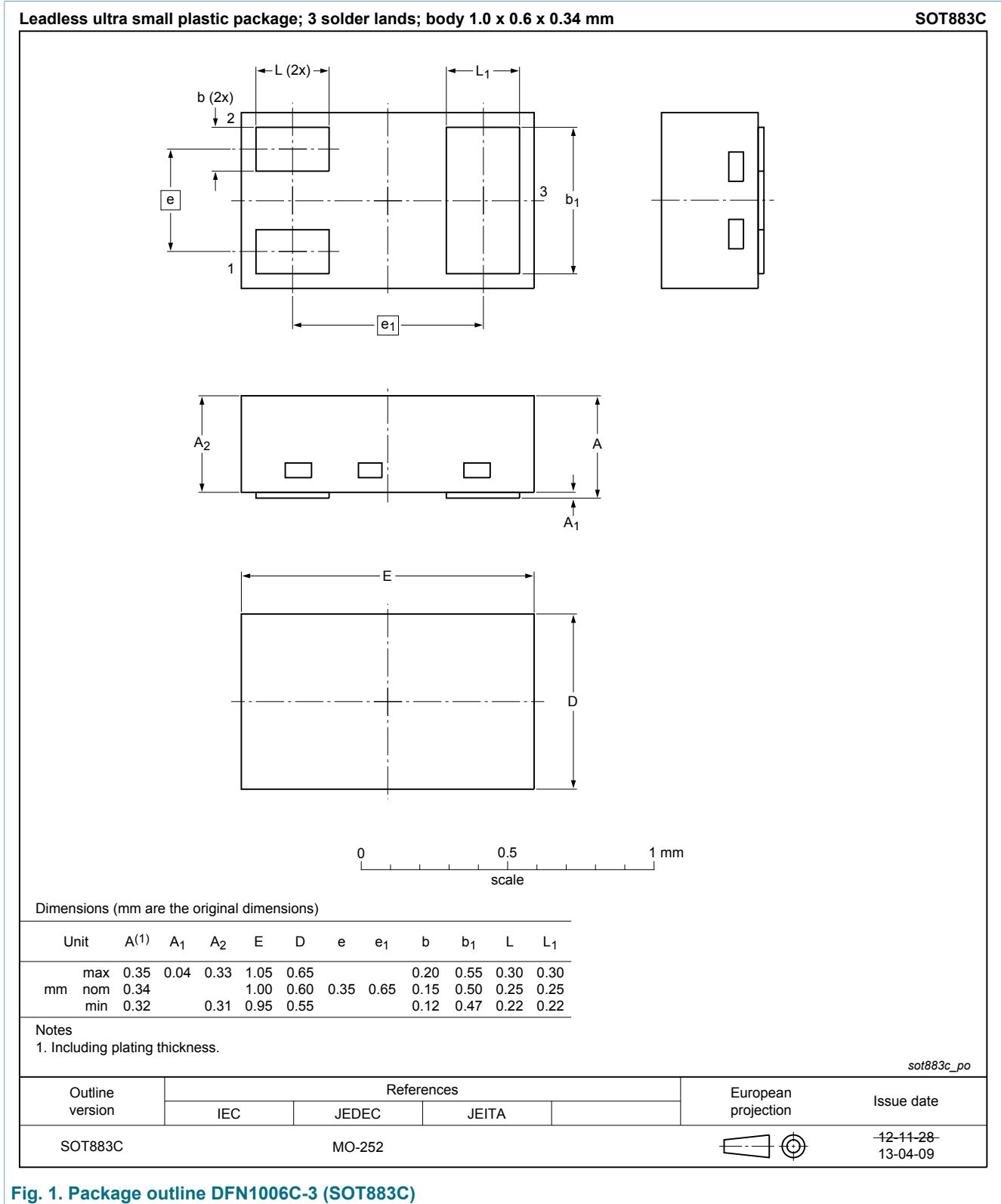


Fig. 1. Package outline DFN1006C-3 (SOT883C)

### 3. Legal information

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